



NOTES;

1. ALL EXPOSED METALLIZED AREA SHALL BE GOLD PLATED 60 MICRO INCH MIN. THK. OVER NICKEL PLATED.
2. SEAL RING FLATNESS .003 MAX.
3. SEAL RING AND DIE ATTACH PAD ARE NOT GROUND TO A LEAD.

S=0  
D=0

AN-20C

MODIFICATIONS						NAME	20LEAD CHIP CARRIER (.215 SQ. CAV.)	TOLERANCES: UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE
						SCALE	10/1	±1% N.L.T ±.005	S.M	UE. K.H	M.S	MAR.16.'99
						MATERIAL	KYOCERA A-440	THIRD ANGLE PROJECTION				
	CHANGE	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.	PB-23741		SHEET	1/1